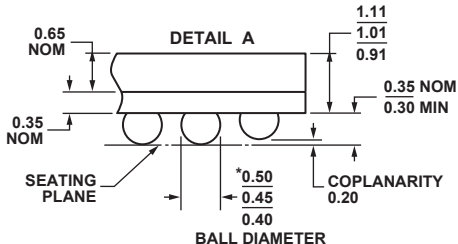
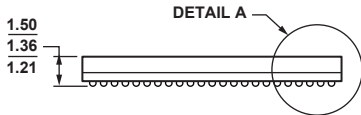
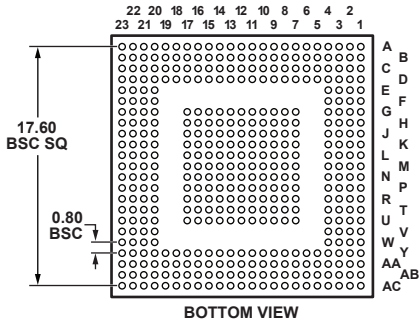
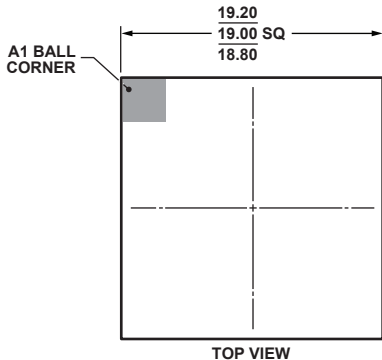


**425-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(BC-425-1)**

Dimensions shown in millimeters



*COMPLIANT TO JEDEC STANDARDS MO-205 WITH THE EXCEPTION TO PACKAGE BALL THICKNESS.